





>>> SMARTPHONE >>> NETWORK COVERAGE >>> AUTONOMOUS DRIVING >>> INDUSTRY 4.0 >>>





## WITH THE RIGHT SYSTEM INTO A FAST FUTURE

#### Thermal processes with or without vacuum

# Reliable connections for high-mass components

- > High heat transfer
- › Large masses
- > Small delta T
- > Process reliability
- > Void-free soldering

## Soldering of electronic assemblies with vacuum for void reduction

- > Lower operating temperatures
- > Better heat transfer
- > Extended service life

## The 3-in-1 solution for safe soldering processes – even with complex boards

- > Efficient heating of high thermal masses
- > Safe process design
- > High flexibility in profiling



Condenso | Vapor Phase Soldering



VisionXP+ Vac | Convection Soldering



TripleX | Convection Soldering

### Your partner for process solutions

# 5G technology

5G plays a fundamental role in the future digitalisation of many areas of life. Whether autonomous driving, the use of mobile devices or networking in industry and communication: the mobile communications standard 5G creates new opportunities, but also challenges for the production of electronic components.

When it comes to the production of high-performance electronics, transmission masts, smart-phones or electrical drive units, our customers rely on the experience of Rehm Thermal Systems.

Bonding, sealing, protecting, drying, curing, reflow soldering, deoxidation, testing and inspection: We offer innovative solutions and technologies for your individual requirements and beyond and are your partner for the joint path to the 5G future.

- > 7000

  Production machines in the field
- > 600
  Creative minds for your requirements
- > 33

  Years as a technology leader
- > **8**Process areas for your technology

#### Material application and drying | Curing

#### Different material application methods

- $\rightarrow$  Bonding, dispensing and potting
- > Selective Conformal Coating
- → 3D Filling

- > Micro-dispensing
- > Bonding of SMD components
- > Underfill



